



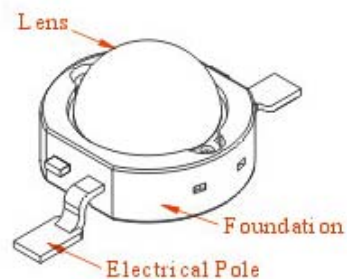
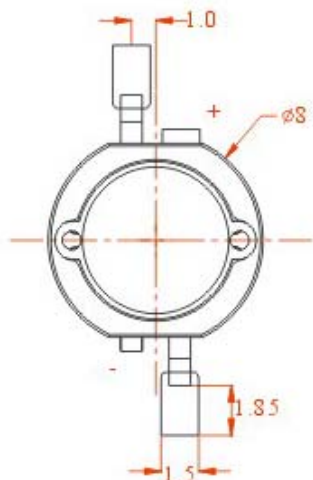
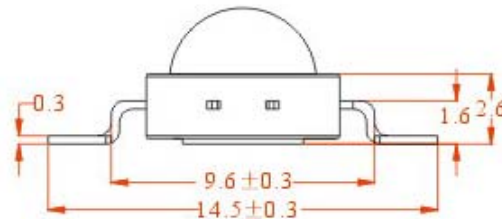
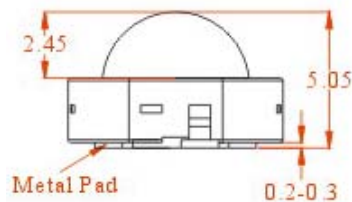
Preliminary Information

HEXAGONAL HIGH POWER UV-LED APG2C1 UV-Series



- Designed for continuous current of 350mA
- beam angle: +/-75°, lambertian silicone lens
- Silicone lens, ageing proof to UV radiation
- chip size 1 x 1mm
- 8 mm base diameter
- Instant light (less then 100ns)

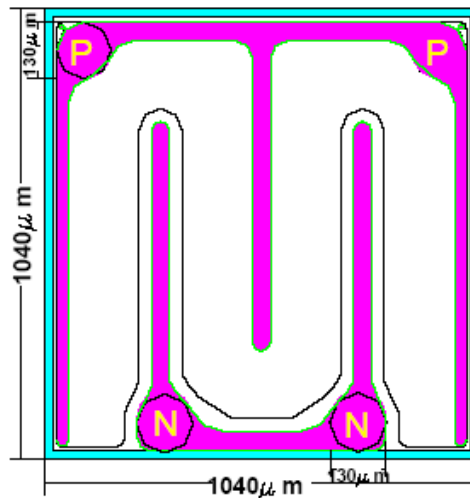
Mechanical Dimensions:





Chip Description

Substrate: sapphire
Epitaxial: GaN based material
Pad material: Au alloy
Chip size: 1040 ±20(μm) x 1040 ±20 (μm)
P and N pad size: Φ 130 ±10(μm)



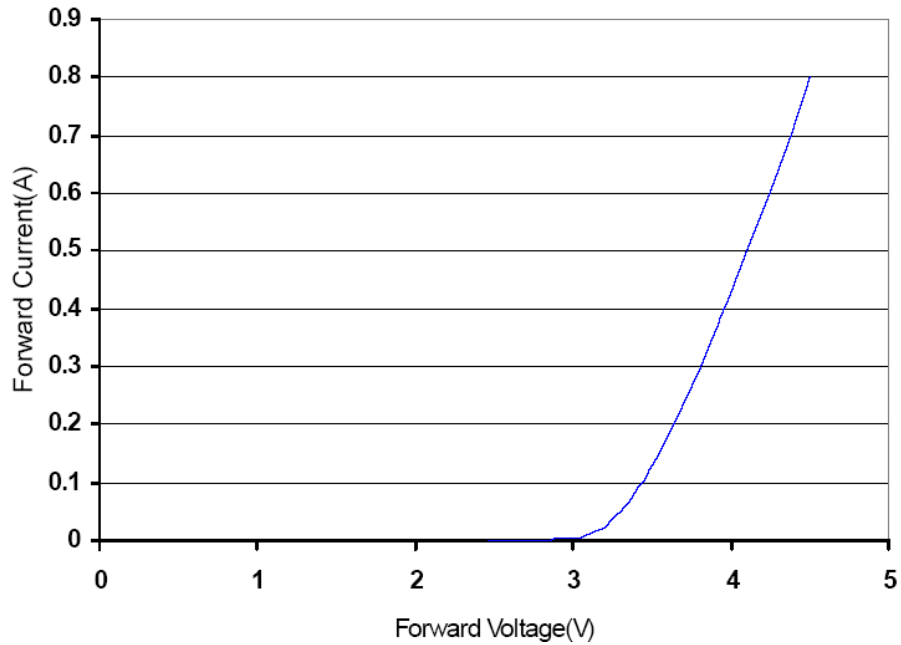
Unit : um

Optical-Electrical Characteristics (Tc = 25°C)

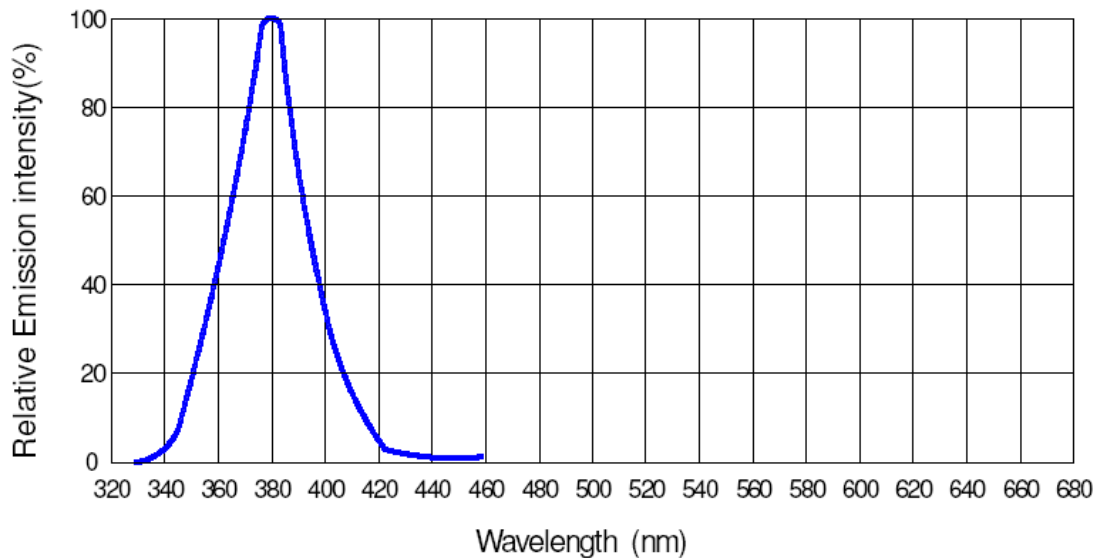
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Power Dissipation	P _d	cw	-	1	-	W
Forward Current	I _f	cw	-	350	-	mA
Forward Voltage	U _f	I _f = 350 mA	3.5	3.7	4.0	V
Leakage Current	I _r	V _r = -5V		<10		μA



Forward Voltage vs. Forward Current



Spectral Distribution:





Specific Optical Output Power (Tc = 25°C)

Model	SYMBOL	TEST CONDITION	TYP	UNIT
APG2C1-365	P _o	I _f = 350 mA	25	mW
APG2C1-375	P _o	I _f = 350 mA	55	mW
APG2C1-385	P _o	I _f = 350 mA	75	mW
APG2C1-395	P _o	I _f = 350 mA	95	mW
APG2C1-405	P _o	I _f = 350 mA	105	mW



- ◆ This UV LED during operation radiates intense UV light.
- ◆ Do not look directly into the UV light during operation of device. This can be harmful to the eyes even for brief period due to the intense UV light.
- ◆ If viewing the UV light is necessary, please use UV filtered glasses to avoid damage by the UV light.
- ◆ Please affix a caution label to your product to that effect, if the UV LED in your product might be viewed directly,
- ◆ Avoid direct eye exposure to UV light.
- ◆ Keep out of reach of children.

Soldering heat reliability □ DIP □ Please refer to the following figure

